

LIQUID CRYSTAL SEALING MATERIAL COMPOSITION

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- European:

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Abstract of JP2000347203

PROBLEM TO BE SOLVED: To provide a liquid crystal sealing material composition which is capable of dealing with liquid crystal display elements (cells) produced by a single wafer press thermal adhesion system and permits the production of the homogeneous and high-quality liquid crystal display elements exhibiting high adhesive seal reliability. **SOLUTION:** The ion conductivity of an aqueous solution obtained by intimately mixing an epoxy resin composition and pure water of this liquid crystal sealing material composition is ≤ 1 mS/m, the viscosity of a B stage composition is 50 to 10000 Pa.s at 80 to 100 deg.C, the coefficient of thermal expansion of the cured matter of the composition is $\leq 10 \times 10^{-5}$ mm/mm/deg.C, the thermal deformation temperature Tg is ≥ 100 deg.C, the 80 deg.C moisture vapor transmission rate of the cured body is ≤ 200 g/m².24 hrs. The composition consists of an epoxy resin having an average ≥ 1.2 epoxy group in the molecule, rubber-like polymer particles (diameter below 5 μ m) of ≤ 0 deg.C in softening point, an inorganic filler, a thermally active latent epoxy hardener and high softening point (≥ 50 deg.C) polymer particulates (diameter below 2 μ m).

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